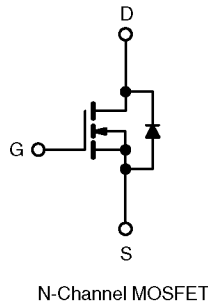
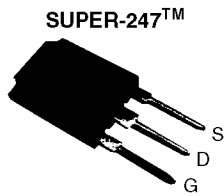


Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	600	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10$ V	0.110
Q_g (Max.) (nC)	330	
Q_{gs} (nC)	84	
Q_{gd} (nC)	150	
Configuration	Single	



FEATURES

- Low Gate Charge Q_g Results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Enhanced Body Diode dV/dt Capability
- Lead (Pb)-free Available



RoHS*
COMPLIANT

APPLICATIONS

- Hard Switching Primary or PFC Switch
- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching
- Motor Drive

ORDERING INFORMATION	
Package	Super-247™
Lead (Pb)-free	IRFPS40N60KPbF
	SiHFPS40N60K-E3
SnPb	IRFPS40N60K
	SiHFPS40N60K


ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	600	V	
Gate-Source Voltage	V_{GS}	± 30		
Continuous Drain Current	V_{GS} at 10 V	$T_C = 25$ °C	A	
		$T_C = 100$ °C		
Pulsed Drain Current ^a	I_{DM}	160		
Linear Derating Factor		4.5	W/°C	
Single Pulse Avalanche Energy ^b	E_{AS}	600	mJ	
Repetitive Avalanche Current ^a	I_{AR}	40	A	
Repetitive Avalanche Energy ^a	E_{AR}	57	mJ	
Maximum Power Dissipation	$T_C = 25$ °C	P_D	570	W
Peak Diode Recovery dV/dt^c		dV/dt	7.5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}		- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s		300 ^d	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting $T_J = 25$ °C, $L = 0.84$ mH, $R_G = 25$ Ω , $I_{AS} = 38$ A, $dV/dt = 5.5$ V/ns (see fig. 12a).
- $I_{SD} \leq 38$ A, $dI/dt \leq 150$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	40	°C/W
Case-to-Sink, Flat, Greased Surface	R_{thCS}	0.24	-	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.22	

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		600	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$		-	0.63	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		3.0	-	5.0	V
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 30\text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 600\text{ V}, V_{GS} = 0\text{ V}$		-	-	50	μA
		$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	250	
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 24\text{ A}^b$	-	0.110	0.130	Ω
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 24\text{ A}^b$		21	-	-	S
Dynamic							
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V},$ $V_{DS} = 25\text{ V},$ $f = 1.0\text{ MHz}$, see fig. 5		-	7970	-	pF
Output Capacitance	C_{oss}			-	750	-	
Reverse Transfer Capacitance	C_{riss}			-	75	-	
Output Capacitance	C_{oss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$	-	9440	-	pF
Effective Output Capacitance	$C_{oss\text{ eff.}}$		$V_{DS} = 480\text{ V}, f = 1.0\text{ MHz}$	-	200	-	
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}$	$I_D = 38\text{ A}, V_{DS} = 480\text{ V},$ see fig. 6 and 13 ^b	-	-	330	nC
Gate-Source Charge	Q_{gs}			-	-	84	
Gate-Drain Charge	Q_{gd}			-	-	150	
Turn-On Delay Time	$t_{d(on)}$		$V_{DD} = 300\text{ V}, I_D = 38\text{ A},$ $R_G = 4.3\text{ }\Omega$, see fig. 10 ^b	-	47	-	ns
Rise Time	t_r			-	110	-	
Turn-Off Delay Time	$t_{d(off)}$			-	97	-	
Fall Time	t_f	-		60	-		
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	40	A
Pulsed Diode Forward Current ^a	I_{SM}			-	-	160	
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 38\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	1.5	V
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}$	$I_F = 38\text{ A}, di/dt = 100\text{ A}/\mu\text{s}$	-	630	950	ns
		$T_J = 125\text{ }^\circ\text{C}$		-	730	1090	
Body Diode Reverse Recovery Charge	Q_{rr}	$T_J = 25\text{ }^\circ\text{C}$		-	14	20	μC
		$T_J = 125\text{ }^\circ\text{C}$		-	17	25	
Body Diode Recovery Current	I_{RRM}	$T_J = 25\text{ }^\circ\text{C}$		-	39	58	A
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.
- c. $C_{oss\text{ eff.}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

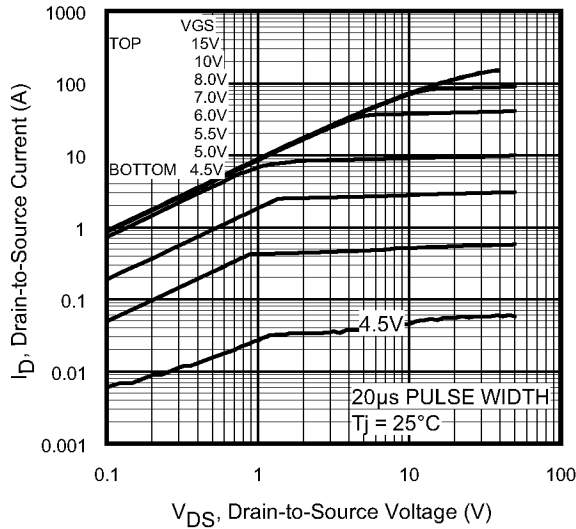


Fig. 1 - Typical Output Characteristics

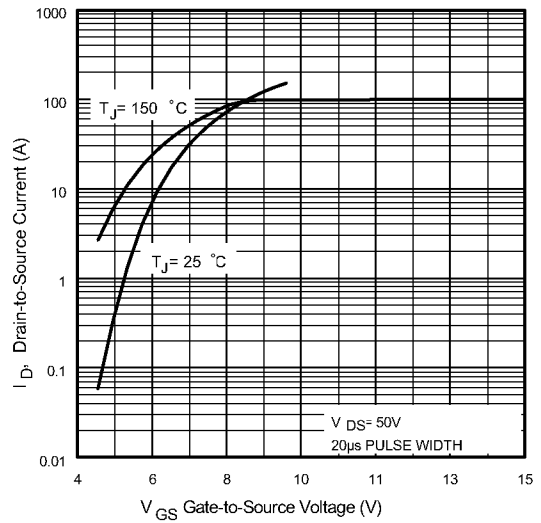


Fig. 3 - Typical Transfer Characteristics

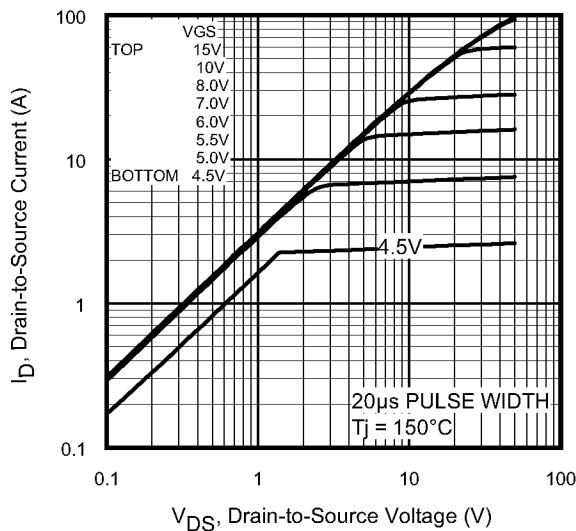


Fig. 2 - Typical Output Characteristics

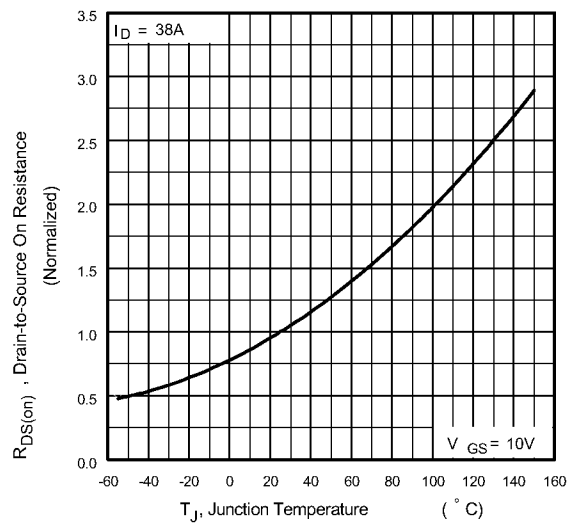


Fig. 4 - Normalized On-Resistance vs. Temperature

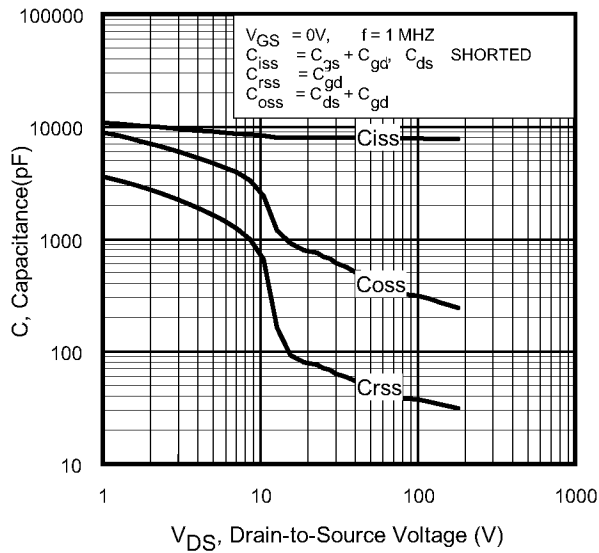


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

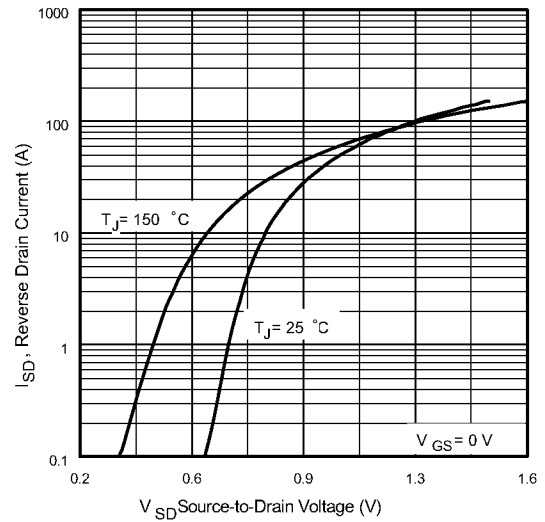


Fig. 7 - Typical Source-Drain Diode Forward Voltage

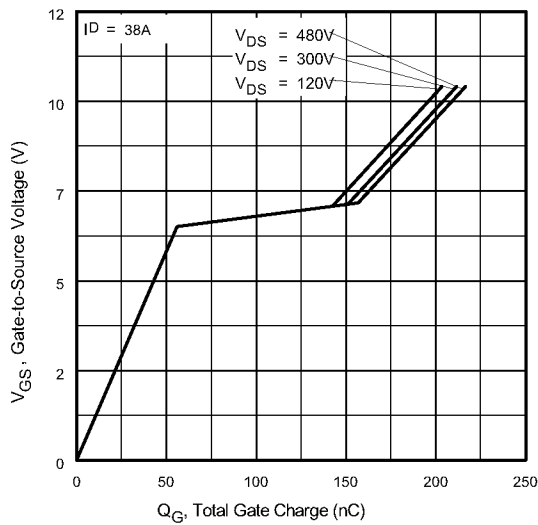


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

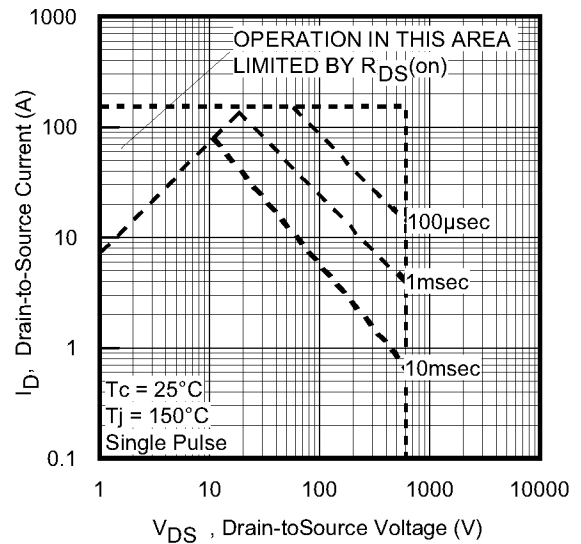


Fig. 8 - Maximum Safe Operating Area

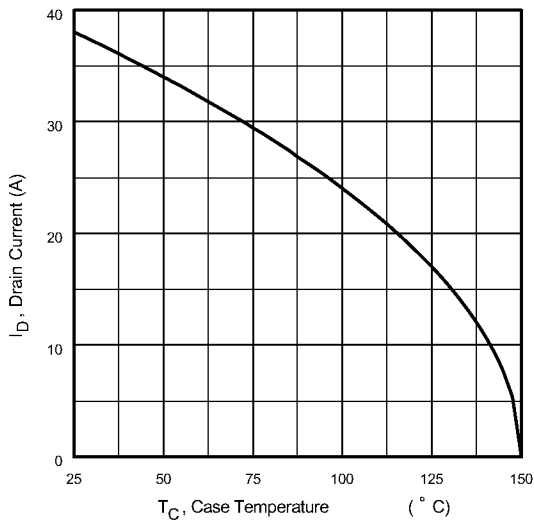


Fig. 9 - Maximum Drain Current vs. Case Temperature

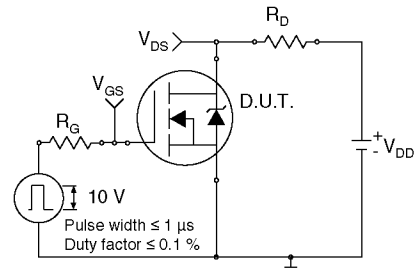


Fig. 10a - Switching Time Test Circuit

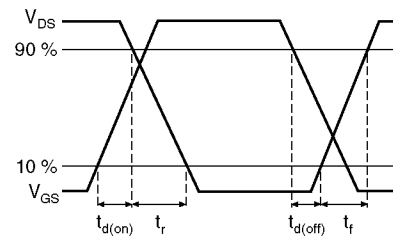


Fig. 10b - Switching Time Waveforms

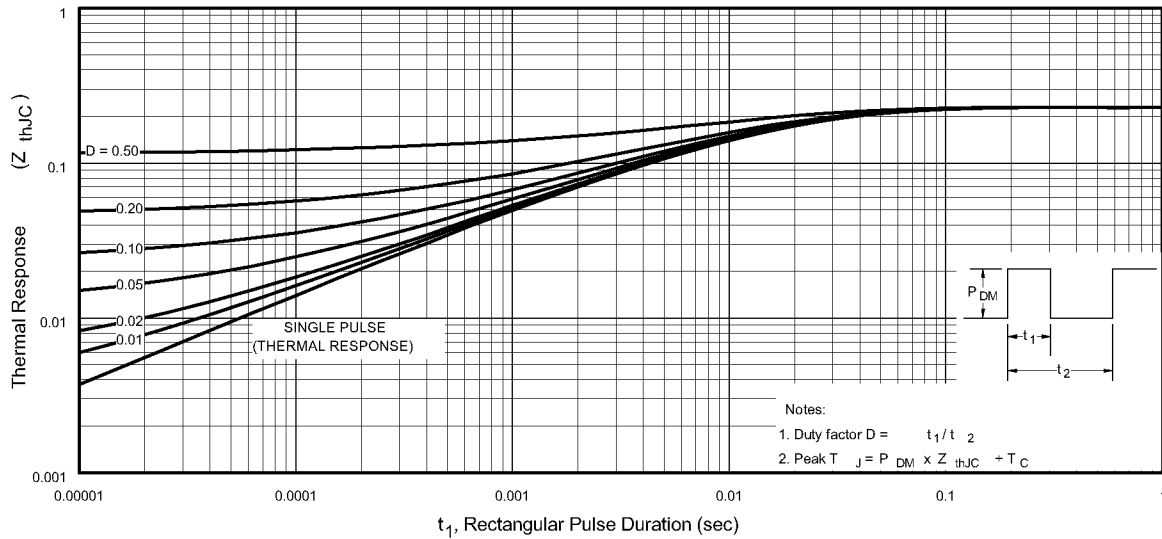


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

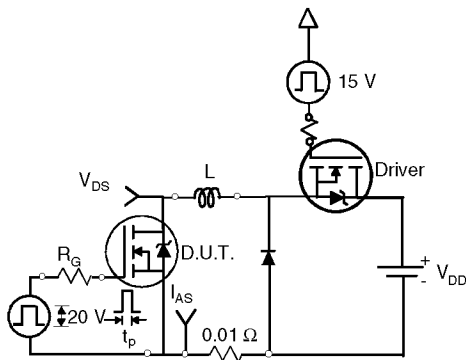


Fig. 12a - Unclamped Inductive Test Circuit

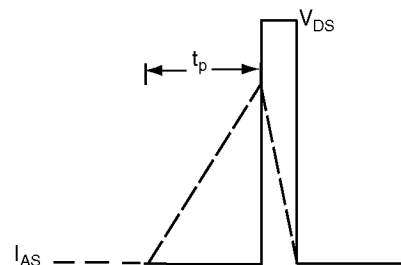


Fig. 12b - Unclamped Inductive Waveforms

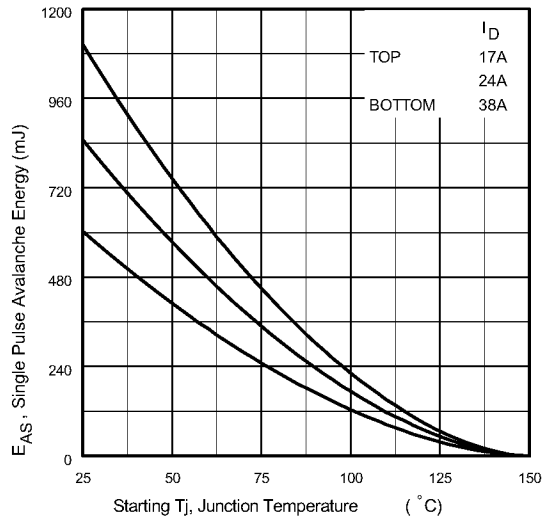


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

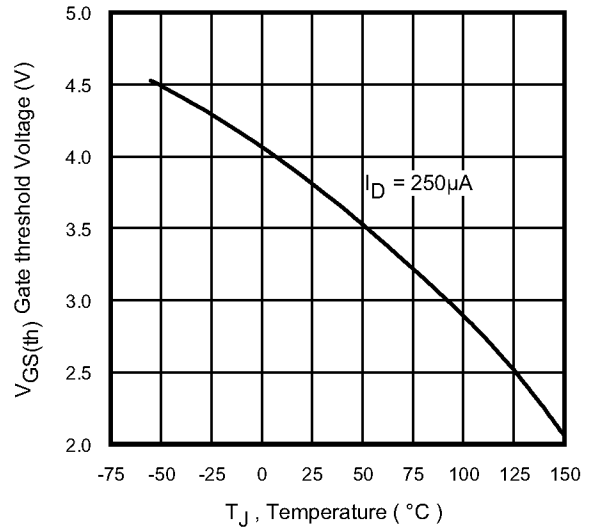


Fig. 12d - Threshold Voltage vs. Temperature

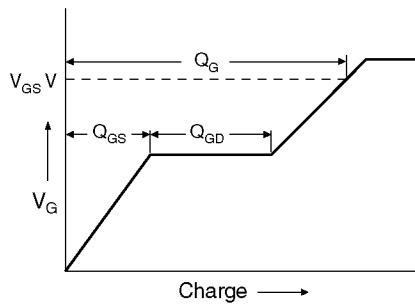


Fig. 13a - Basic Gate Charge Waveform

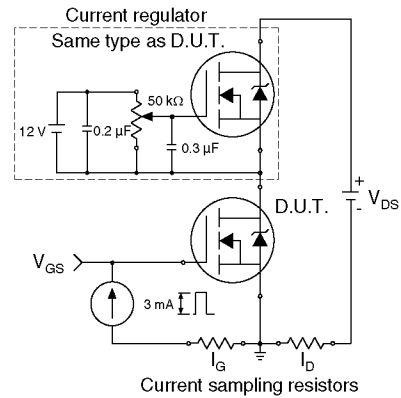


Fig. 13b - Gate Charge Test Circuit